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### **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31A475KOHNNNE

• Product : Multi-layer Ceramic Capacitor • Descriptiont : CAP, 4.7 µF, 16V, ±10%, X5R, 1206

#### A. Samsung Part Number

<u>CL</u> <u>31</u> <u>A</u> <u>475</u> <u>K</u> <u>O</u> <u>H</u> <u>N</u> <u>N</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor								
2	Size	1206 (inch c	code)	L: 3.2	± 0.2	mm	W:	1.6	± 0.2	mm
3	Dielectric	X5R		8	Inner e	ectrode		Ni		
4	Capacitance	<b>4.7</b> μF			Termin	ation		Cu		
(5)	Capacitance	±10 %			Plating			Sn 10	0%	(Pb Free)
	tolerance			9	Produc	t		Norm	al	
6	Rated Voltage	16 V		10	10 Special			Reserved for future use		future use
7	Thickness	1.6 ± 0.2	mm	11)	Packaging			Embossed Type, 7" reel		

#### **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition					
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms					
Tan δ (DF)	0.075 max.						
Insulation	10,000Mohm or 100Mohm⋅μF	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X5R						
characteristics	(From -55℃ to 85℃, Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition					
Vibration Test Capacitance change: within ±5		Amplitude : 1.5mm					
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)					
		2hours × 3 direction (x, y, z)					
Moisture	Capacitance change: within ±12.5%	With rated voltage					
Resistance	Tan δ : 0.1 max	40±2℃, 90~95%RH, 500+12/-0hrs					
	IR: 500Mohm or 25Mohm · μF						
	Whichever is Smaller						
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage					
Resistance	Tan δ : 0.1 max	Max. operating temperature					
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F						
	Whichever is Smaller	1000+48/-0hrs					
Temperature	Capacitance change: within ±7.5%	1 cycle condition					
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C					
		→ Max. operating temperature → 25°C					
		5 cycle test					

#### C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}\text{C}$  , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.